



Material Content Data Sheet



Sales Product Name	BSF035NE2LQ			Issued		11. November 2019		
MA#	MA001050858							
Package	MG-WDSO-N-2-3			Weight*		49.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.497	3.05	3.05	30532	30532
leadframe	non noble metal	copper	7440-50-8	45.114	92.01	92.01	919959	919959
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.23		2339	
	noble metal	silver	7440-22-4	0.456	0.93	1.16	9302	11641
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1580	1580
solder	non noble metal	copper	7440-50-8	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.031	0.06		638	
	non noble metal	tin	7440-31-5	1.006	2.05	2.12	20510	21254
glue	plastics	acrylic resin	-	0.090	0.18		1843	
	noble metal	silver	7440-22-4	0.555	1.13	1.31	11323	13166
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1868	1868
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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